

Teo Cheng Kim Scholarship

In 2018, Professor Ho Teck Hua made an endowed gift of S\$250,000 to the Faculty of Engineering (now College of Design and Engineering) to support a scholarship, in memory of his late mother, Madam Teo Cheng Kim.

The bond-free scholarship of up to S\$8,350 per annum (subject to the availability of the distributable return from the capital sum) is awarded to deserving students for their normal course duration. This scholarship is **by invitation only**. Shortlisted students will be invited to submit the necessary documentation and may be required to attend an interview.

Selection Criteria

The applicant should:

1. Be a full-time engineering undergraduate in his/her first year of study (i.e., matriculation year).
2. Possess outstanding Singapore-Cambridge GCE A Level, local polytechnic diploma, International Baccalaureate diploma, NUS High School diploma or equivalent qualification. Participation in extra-curricular activities or community service will be considered favourably.
3. Not concurrently hold any other scholarship, fellowship, bursary, grant, award or allowance, without prior written approval from NUS.

While there is no bond attached to the Teo Cheng Kim Scholarship, students are required to take up the MOE Tuition Grant to receive the scholarship. Singapore Permanent Residents and international students who take up the MOE Tuition Grant will be bonded under the terms of the Tuition Grant – to work for a Singapore-registered company for three years immediately after graduation.

Scholarship recipients need to maintain a Grade Point Average (GPA) of 3.50 and above in each academic year to continue receiving the scholarship.